



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20191211001.1
Qualification of UTL3 as an additional AT site for Select Devices
Change Notification / Sample Request

Date: January 23, 2020
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team
SC Business Services




20191211001.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CC2541F256RHAR	null
CC2541F256RHAT	null
TPS22990DMLT	null
TPS3895ADRYR	null
TPS61252DSGR	null
TPS61252DSGT	null
TPS62260DRVR	null
TPS62260DRVT	null
BQ24308DSGT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20191211001.1			PCN Date:	Jan. 23, 2020				
Title:	Qualification of UTL3 as an additional AT site for Select Devices								
Customer Contact:	PCN Manager	Dept:	Quality Services						
Proposed 1st Ship Date:	April 23, 2020	Estimated Sample Availability:	Date provided at sample request						
Change Type:									
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site				
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material				
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process				
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site				
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials				
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process				
PCN Details									
Description of Change:									
Texas Instruments is pleased to announce the qualification of UTL3 as an additional assembly site for the list of devices below. There are no construction differences between the current and new site.									
Reason for Change:									
Continuity of Supply									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):									
None									
Anticipated impact on Material Declaration									
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp						
Changes to product identification resulting from this PCN:									
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City						
UTAC1	NSE	THA	Bangkok						
UTAC3	UT3	THA	Chachoengsao						
Sample product shipping label (not actual product label)									
   <div style="display: flex; justify-content: space-between;"> <div style="width: 30%;"> <p>MADE IN: Malaysia 2DC: 20:</p> <table border="1" style="font-size: small;"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39 LBL: 5A (L)T0:1750</p> </div> <div style="width: 65%;"> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS</p> </div> </div>						MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04
MSL 2 /260C/1 YEAR	SEAL DT								
MSL 1 /235C/UNLIM	03/29/04								
Product Affected:									
BQ24308DSGR	INA210AIRSWT	TPS3420DDRYR	TPS61252DSGR						
BQ24308DSGT	INA214AIRSWR	TPS3420DDRYT	TPS61252DSGT						
CC2541F256RHAR	INA214AIRSWT	TPS3895ADRYR	TPS62260DRVR						
CC2541F256RHAT	LM27402SQ/NOPB	TPS3895ADRYT	TPS62260DRVT						

INA199A1RSWR	TPS22990DMLR	TPS3897PDRYR	UCC27201ADMR
INA199A1RSWT	TPS22990DMLT	TPS3897PDRYT	UCC27201ADRMT
INA210AIRSWR			



TI Information
Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CC2541F256RHAR	Qual Device: INA210AIRSWR	Qual Device: TPS22990DMLR
PC	Preconditioning	Level 1 - 260C	-	3/462/0	-
PC	Preconditioning	Level 2 - 260C	-	-	3/693/0
PC	Preconditioning	Level 3 - 260C	3/693/0	-	-
AC	Autoclave, 121C	96 Hours	3/230/0 ¹	3/231/0	3/231/0
BHAST	Biased HAST, 110C	264 Hours	3/230/0 ²	-	3/231/0
ED	Electrical Characterization	Side by side	-	3/90/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	3/231/0	3/231/0
MSL	Moisture Sensitivity	Level 1 - 260C	-	3/36/0	-
MSL	Moisture Sensitivity (Cu Wire)	Level 2 - 260C	-	-	3/36/0
MSL	Moisture Sensitivity (Cu Wire)	Level 3 - 260C	3/36/0	-	-
SA	Salt Atmosphere	24 Hours	3/66/0	-	-
SD	Solderability, Pb-free	Steam age, 8 hours	3/66/0	3/66/0	3/66/0
TC	Temperature Cycle, -65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. site specification)	3/Pass	3/Pass	3/Pass
BPCC	Bond Pad Cratering Check	Post Final Test	3/15/0	3/15/0	3/15/0
DS	Die Shear	Die	3/30/0	-	3/30/0
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0	3/228/0
PD	Physical Dimensions	(per mechanical drawing)	3/15/0	3/15/0	3/15/0
VM	Visual / Mechanical	(per mfg. site specification)	3/36/0	3/36/0	3/36/0
XRAY	X-Ray	Top side only	3/15/0	3/15/0	3/15/0
YLD	FTY and Bin Summary	-	3/Pass	3/Pass	3/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Notes:

1. One device failed post-stress. Bin and failure analysis did not assign root cause to packaging issue, handling, or new factory. Discounted.
2. One device failed post-stress. Unit passed on retest. Discounted.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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